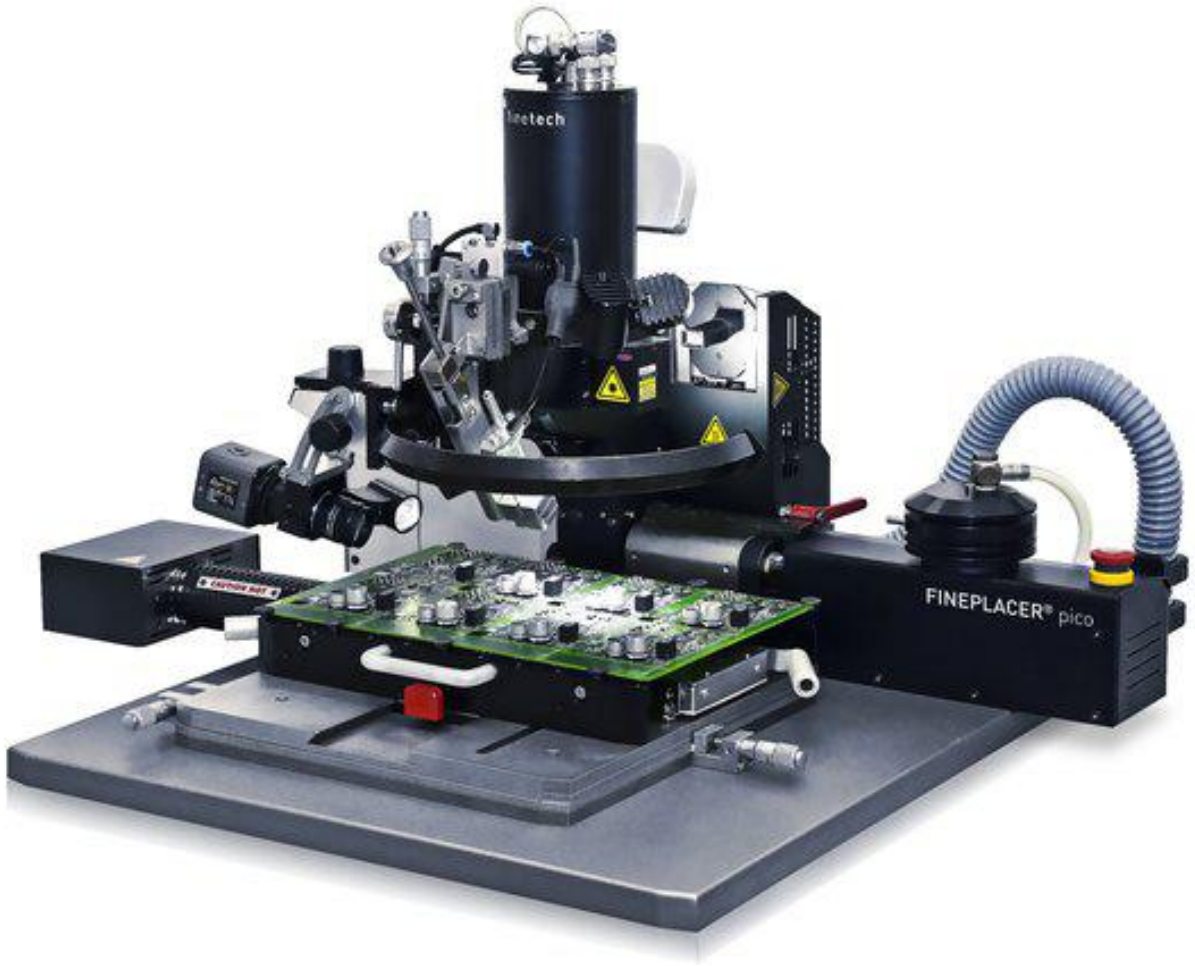
finetech

advanced rework

FINEPLACER® pico rs

High Density Rework Station



FINEPLACER® pico rs

FINEPLACER® pico rs is an enhanced hot air rework station for assembly and rework of all types of SMD components.

The system is a best seller for professional mobile device rework in high density environments. A high level of process modularity allows all rework process steps within one system. The FINEPLACER® pico rs system is at home in R&D, process development, prototyping and production environments.

Application area from 01005 up to large BGA on small to medium sized PCBs, with the goal to have highly reproducible soldering results.

Highlights*

- Industry- leading thermal management
- Components from 0.125 mm x 0.125 mm to 90 mm x 70 mm
- Board sizes up to 400 mm x 234 mm
- High efficiency board heater
- Closed loop force control
- Automated top heater calibration
- Placement accuracy better than 5 µm

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* depending on configuration/application, (1) other values on request and depending on configuration, (2) optional modules

Features

- Automated soldering processes
- Overlay vision alignment system (VAS) with fixed beam splitter
- Modular design
- Integrated Process Management (IPM)
- Real time process observation camera
- Adaptive process library
- Process transfer from system to system

Benefits

- Hands- off component placement, user independent process operation
- Outstanding placement accuracy and instant operation without adjustments
- Provides high level of application flexibility
- Synchronized control of all process related parameters: force, temperature, time, flow, power, process environment and illumination
- Immediate visual feedback reduces process development time
- Fast and easy process development
- Identical results on different machines allow central profile development,administration and distribution

Processes

- Component removal
- Site cleaning
- Re- balling (array, single)
- Paste printing (component, PCB)
- Paste dipping
- Paste dispensing
- Fluxing
- Soldering
- Desoldering

Applications

- Soldering of:
  - BGA, µBGA/ CSP, QFN, DFN, PoP, QFP, PGA, SON
  - Small passives down to 01005
  - RF shields, RF frames
  - Connectors, sockets
  - Sub assemblies, daughter boards
  - Flip Chip (C4)
- Pin in Paste (PiP)
- Trough Hole Reflow (THR)
- Reworkable underfill, conformal coating
- Single ball rework

Technical Specifications

Placement accuracy:	5 µm
Field of view (min)[1]:	11.5 mm x 8.6 mm
Field of view (max)[1]:	69 mm x 53 mm
Component size (min)[1]:	0.125 mm x 0.125 mm
Component size (max)[1]:	50 mm x 50 mm
Thermocouples[2*]:	2-8
Top Heating[2]:	
Power:	900 W
Temperature ramp rate:	1 K/ s - 50 K/ s
Flow range:	10 Nl/ min - 70 Nl/ min
Bottom Heating[2]:	
Power:	1600 W
Heated area (max):	280 mm x 250 mm
Flow range:	32 Nl/ min - 160 Nl/ min

Modules & Options

- Board Printing Tools
- Bottom Heating Modules
- Component Presentation
- Direct Component Printing Module (DCP)
- Dispenser Module
- Flux Transfer Module
- HOTBEAM
- MiniOven 04
- PCB Support
- Process Gas Switching
- Process Start Sensor
- Process Video Module
- Reballing Module
- Solder Removal Module
- Split Field Optics
- Top Heating Module

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